

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	162	257/620,700-702,758,759,797. ccls. and (substrate board chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 18:49
L6	226	257/620,700-702,758,759,797. ccls. and (substrate board chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 18:54
L7	143	"361"/\$.ccls. and (substrate board chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 18:56
L9	180	438/458,460,462,622,623,637, 666.ccls. and (substrate board chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 18:58
L10	941	(substrate board) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3) and (hole via) same (dielectric insulat\$3) and (dic\$3 saw\$3 cut\$4 separat\$3) with (substrate board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 19:00
L11	701	(chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3) and (hole via) same (dielectric insulat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 19:01